DOCKET NO.: 4597

INV.: H. URAGAMI et al.

TITLE: Method of Resin Encapsulation, Apparatus for Resin Encapsulation, Method of Manufacturing Semiconductor Device, and Resin Material

1 of 5

FIG.1A

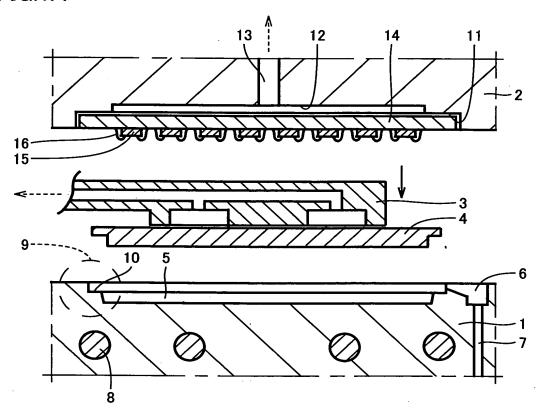


FIG.1B

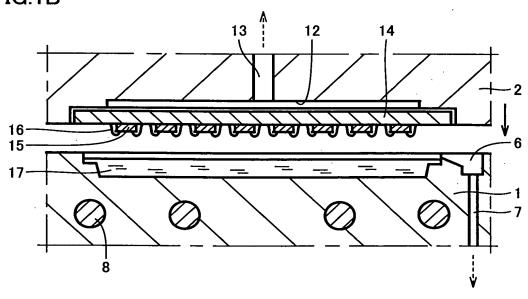


FIG.2A

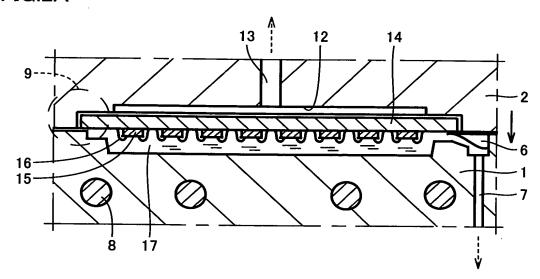
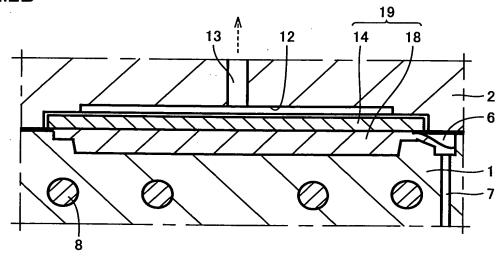
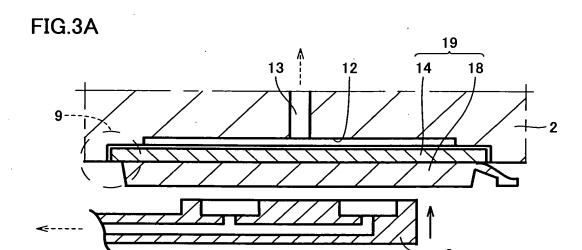


FIG.2B





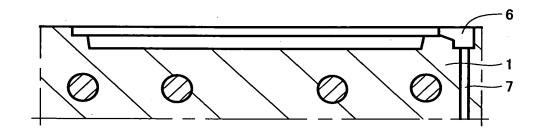


FIG.3B

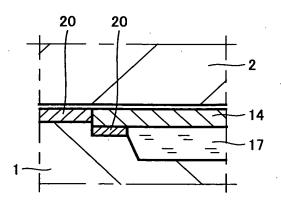


FIG.4A

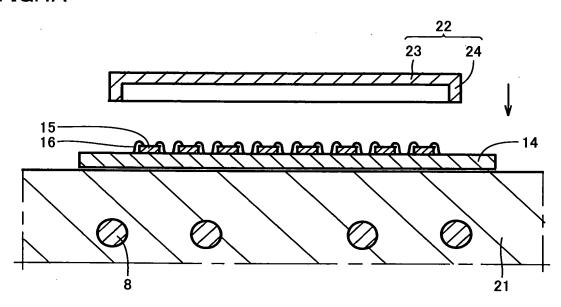


FIG.4B

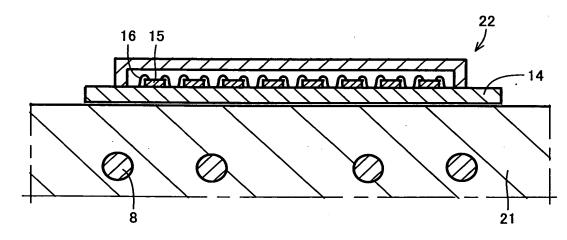


FIG.5A

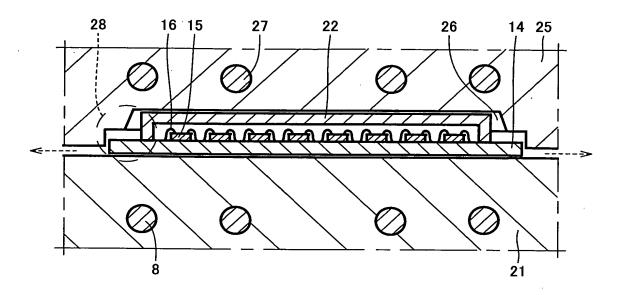


FIG.5B

